



SMT power inductors

Size 10.4 × 10.4 × 3.0 (mm)

Series/Type: **B82464G2**

Date: **June 2012**

SMD

Rated inductance 0.82 ... 330 μ H

Rated current 0.41 ... 6.2 A



Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding welded to terminals

Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics
- Consumer electronics

Terminals

- Base material CuFe2P
- Layer composition Ag, Sn (lead-free)
- Electro-plated

Marking

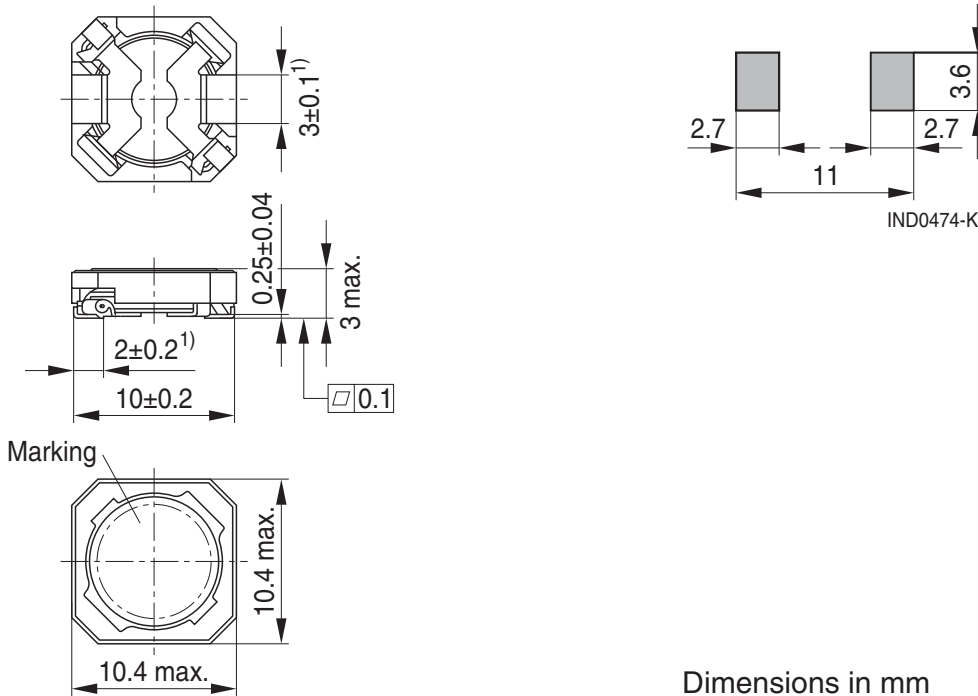
- Marking on component:
Manufacturer, L value (nH, coded),
L tolerance (coded), manufacturing date (YWWD),
two last digits of work order
- Minimum data on reel:
Manufacturer, ordering code, L value,
quantity, date of packing

Delivery mode and packing unit

- 16-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 1250 pcs./reel

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Dimensional drawing and layout recommendation



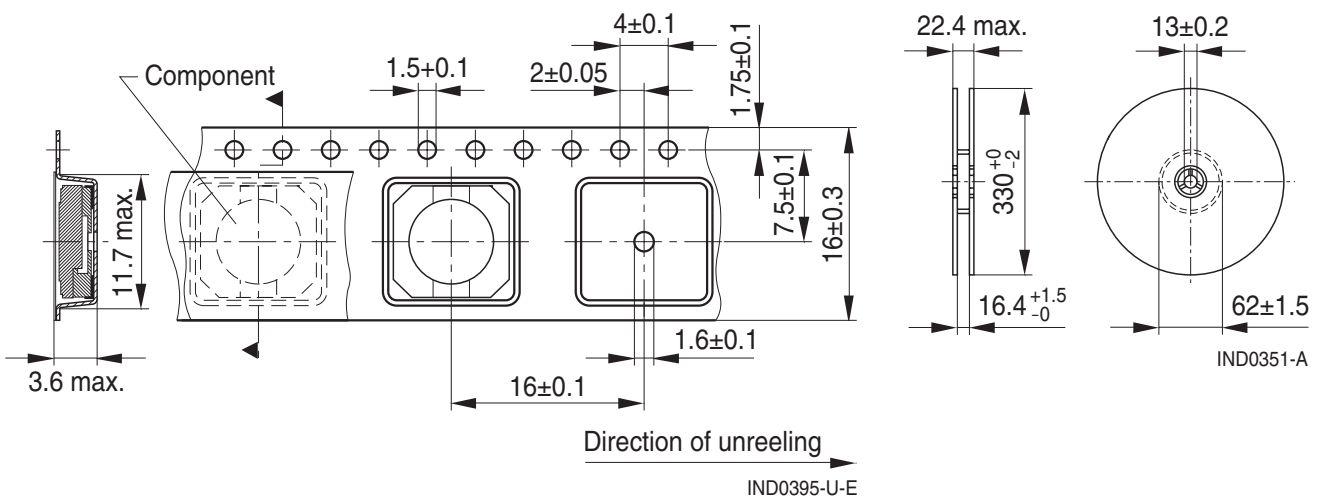
1) Soldering area

IND0475-W-E

Taping and packing

Blister tape

Reel



Dimensions in mm

Technical data and measuring conditions

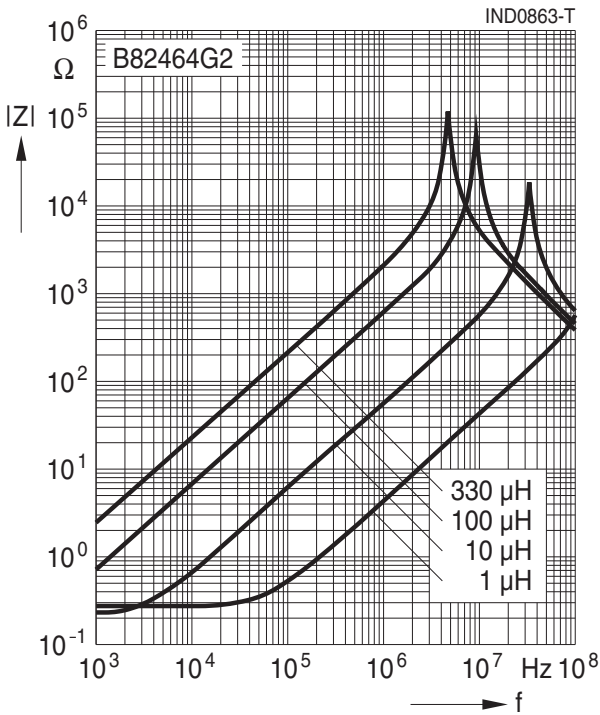
Rated inductance L_R	Measured with impedance analyzer Agilent 4294A at frequency f_L , 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 \pm 5) °C, (5 \pm 0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 1.1 g

Characteristics and ordering codes

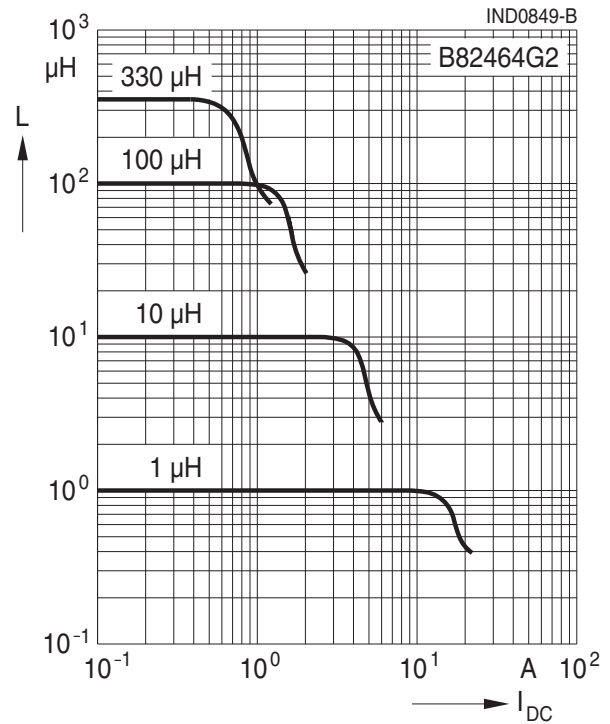
L_R μH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
0.82	$\pm 20\% \triangleq M$	0.1	6.20	7.50	0.0075	B82464G2821M000
1.2		0.1	5.60	6.80	0.009	B82464G2122M000
2.0		0.1	4.50	5.40	0.014	B82464G2202M000
2.7		0.1	3.85	4.25	0.019	B82464G2272M000
3.9		0.1	3.45	3.45	0.027	B82464G2392M000
4.7		0.1	3.10	3.10	0.033	B82464G2472M000
7.5		0.1	2.60	2.65	0.047	B82464G2752M000
10		0.1	2.25	2.25	0.062	B82464G2103M000
15		0.1	1.80	1.85	0.090	B82464G2153M000
22		0.1	1.50	1.52	0.130	B82464G2223M000
33		0.1	1.20	1.25	0.195	B82464G2333M000
47		0.1	1.12	1.10	0.235	B82464G2473M000
68		0.1	0.91	0.88	0.370	B82464G2683M000
100		0.1	0.75	0.73	0.530	B82464G2104M000
150		0.1	0.61	0.59	0.840	B82464G2154M000
220		0.1	0.50	0.49	1.2	B82464G2224M000
330		0.1	0.41	0.40	1.6	B82464G2334M000

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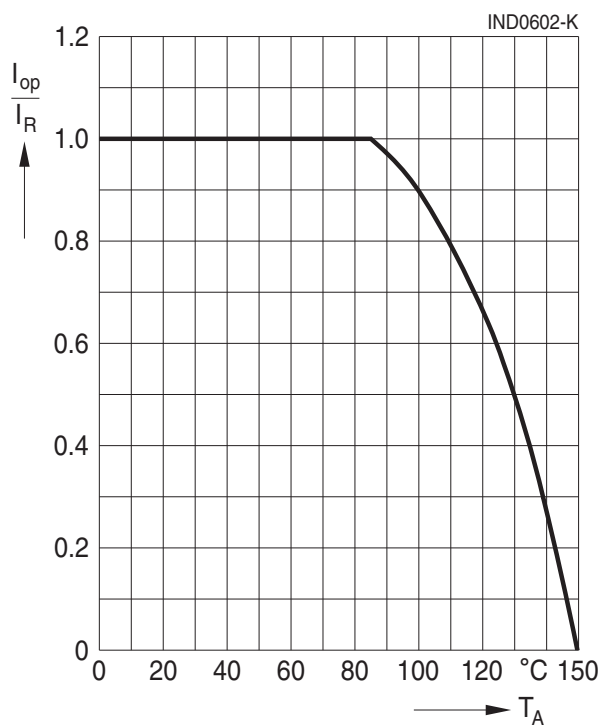
Impedance $|Z|$ versus frequency f
measured with impedance analyzer
Agilent 4294A, typical values at +20 °C



Inductance L versus DC load current I_{DC}
measured with LCR meter Agilent 4275A,
typical values at +20 °C



Current derating I_{op}/I_R
versus ambient temperature T_A
(rated temperature $T_R = +85$ °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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